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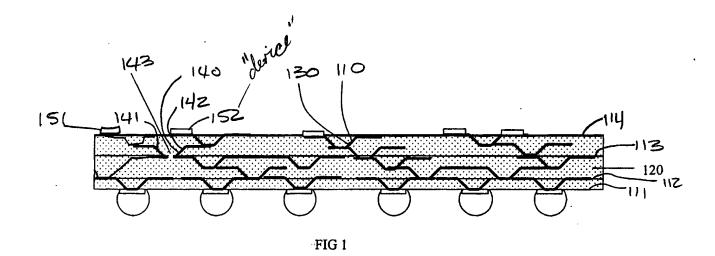
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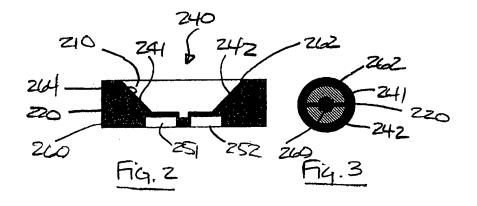
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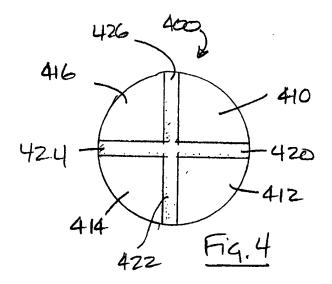
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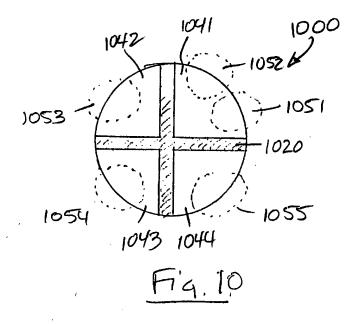
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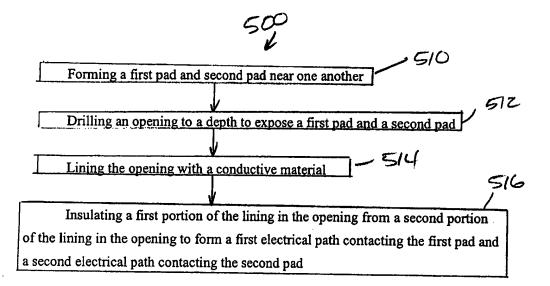


Fig.5

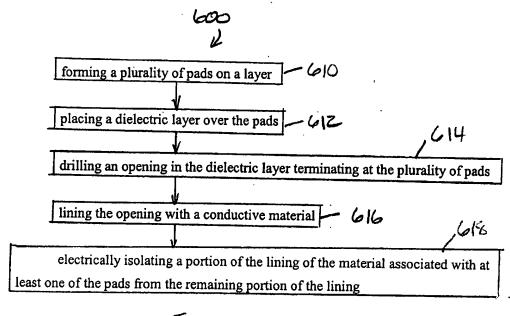
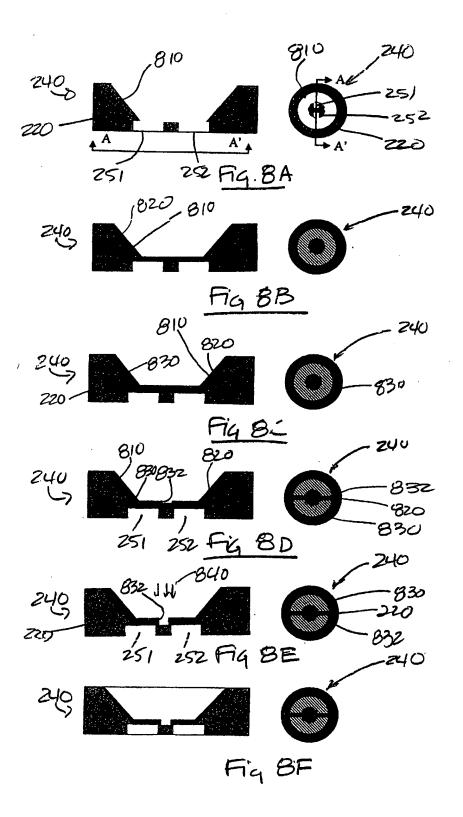
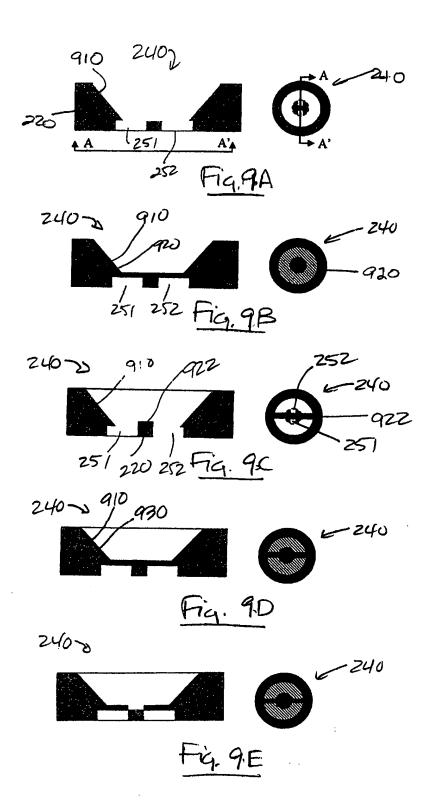
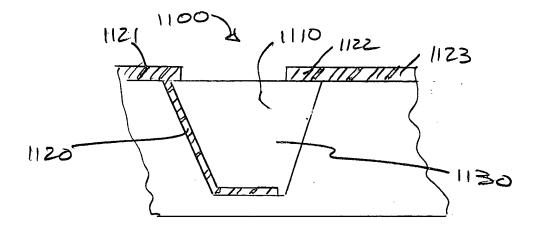
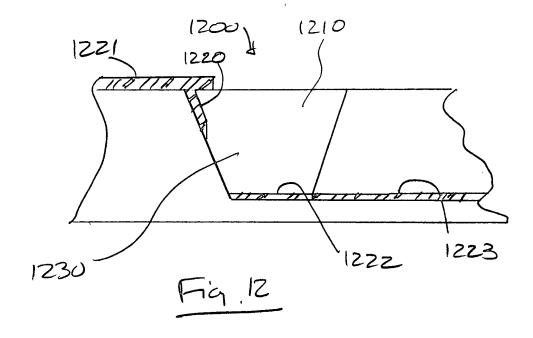


Fig.6









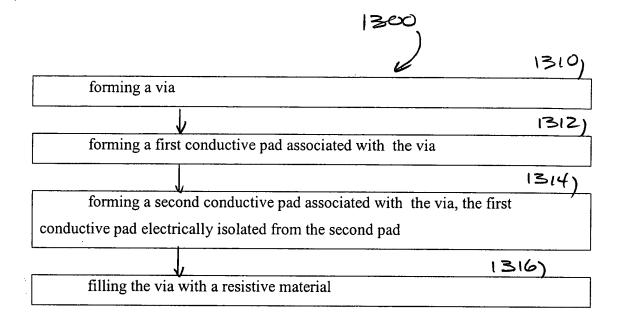
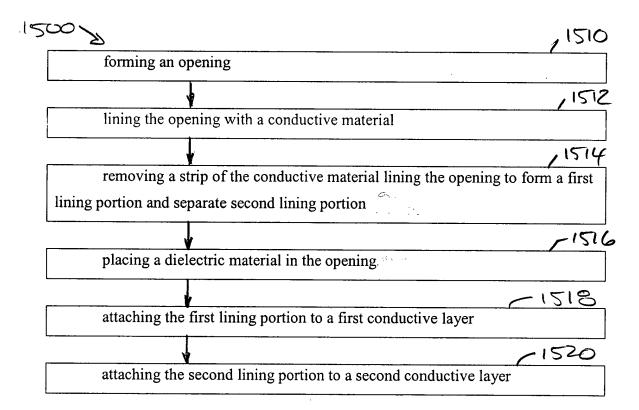
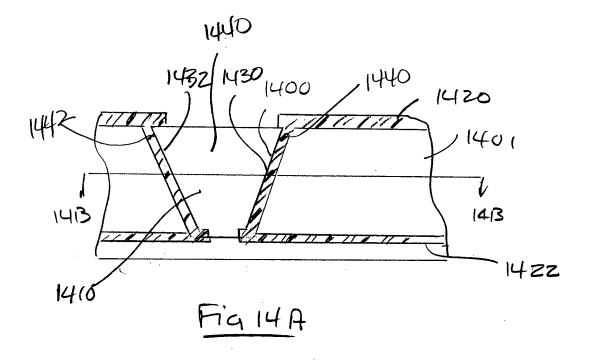
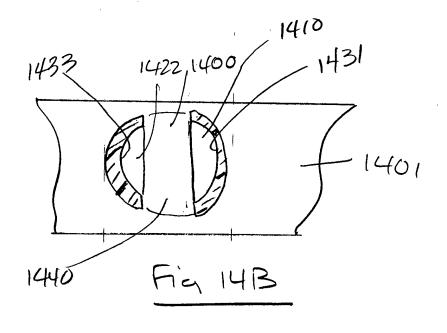


Fig 13



F19.15





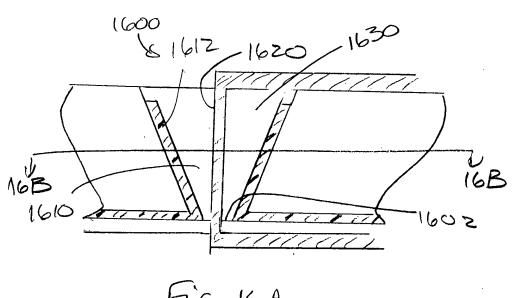
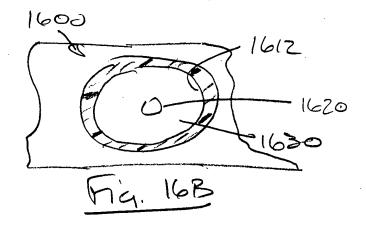


Fig. 16A



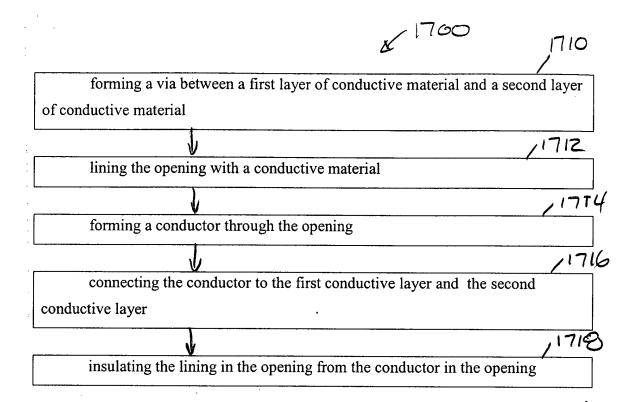


FIG. 17

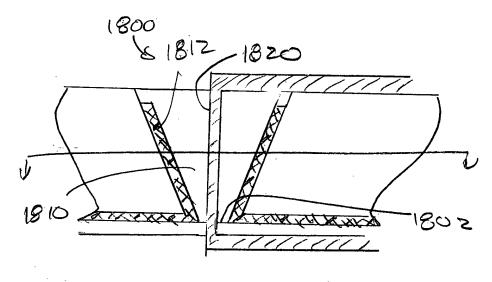
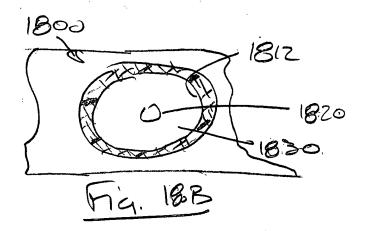
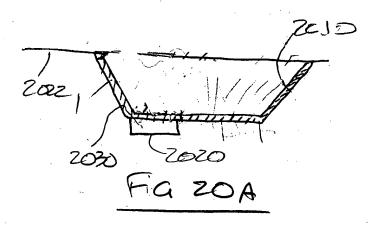


Fig. 18A



Mg.19



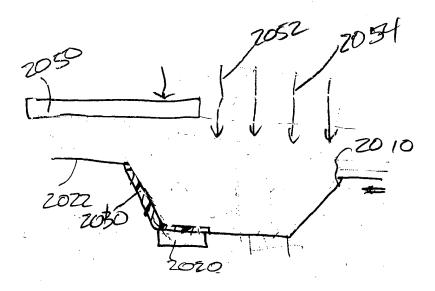
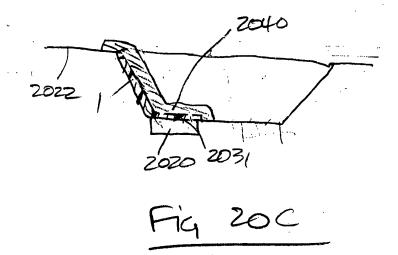


Fig 20B



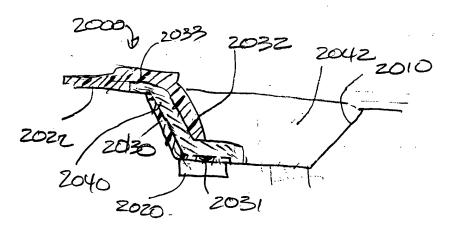


Fig 200

2100 2110 forming a via depositing a first layer of conductive material on inside surface of the via removing a portion of the deposited first layer of conductive material depositing a dielectric material onto the remaining portion of the conductive material and onto the inner surface of the via 2118 removing a second portion of the dielectric material 2120 depositing a second layer of conductive material 2122 attaching one of the first conductive layer and the second conductive layer to an electrical source ~ Z1Z4 filling in the remaining portion of the via with a material.

Fig 2/

FORMING AT LEAST A
PORTION OF AN ELECTRICAL
DEVICE WITHIN THE UIA

Fig 22